



Market, Technical, Cost and Solution Considerations for HSSG

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Outline

- Key Messages
- HSSG Market Requirements
- HSSG Technical Feasibility
- HSSG Cost Considerations
- HSSG Solution Considerations
- Summary



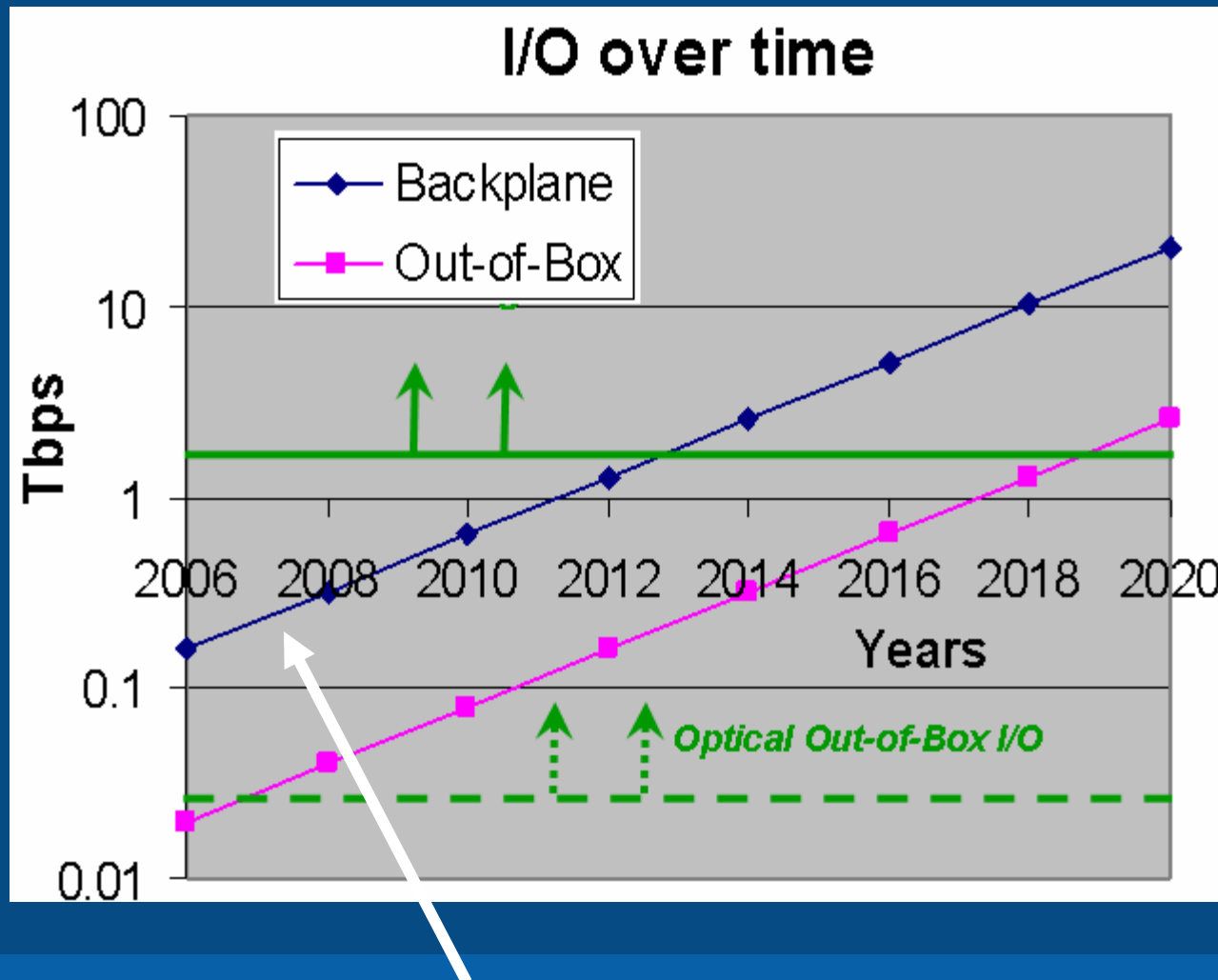
Key Messages

- HSSG should target 100GbE as the next speed bump for Ethernet
 - Needed to get ahead of next generation platform requirements
 - Lower speeds (e.g. 40 GbE) will not be enough
 - HSSG should also address blade backplanes along with data centers, metro and long haul networks
- 100Gb/s Technology is feasible today
 - 40G (OC768) shipping today in volume
 - Optical technology exist today
- Datacom apps likely to drive next generation Ethernet speeds
 - Cost effectiveness of the solution is key for deployment
 - Shorter reach optics for data centers → lowered optics costs



I/O scales with Moore's Law

1. Future I/O BW requirements will drive revolutionary changes!
2. Chip-to-Chip interconnect rates scale with Moore's Law
3. Out of the box or blade rates, follow the chip-to-chip rates
4. By ~2010, we will see 100G backplane data rate reqmts

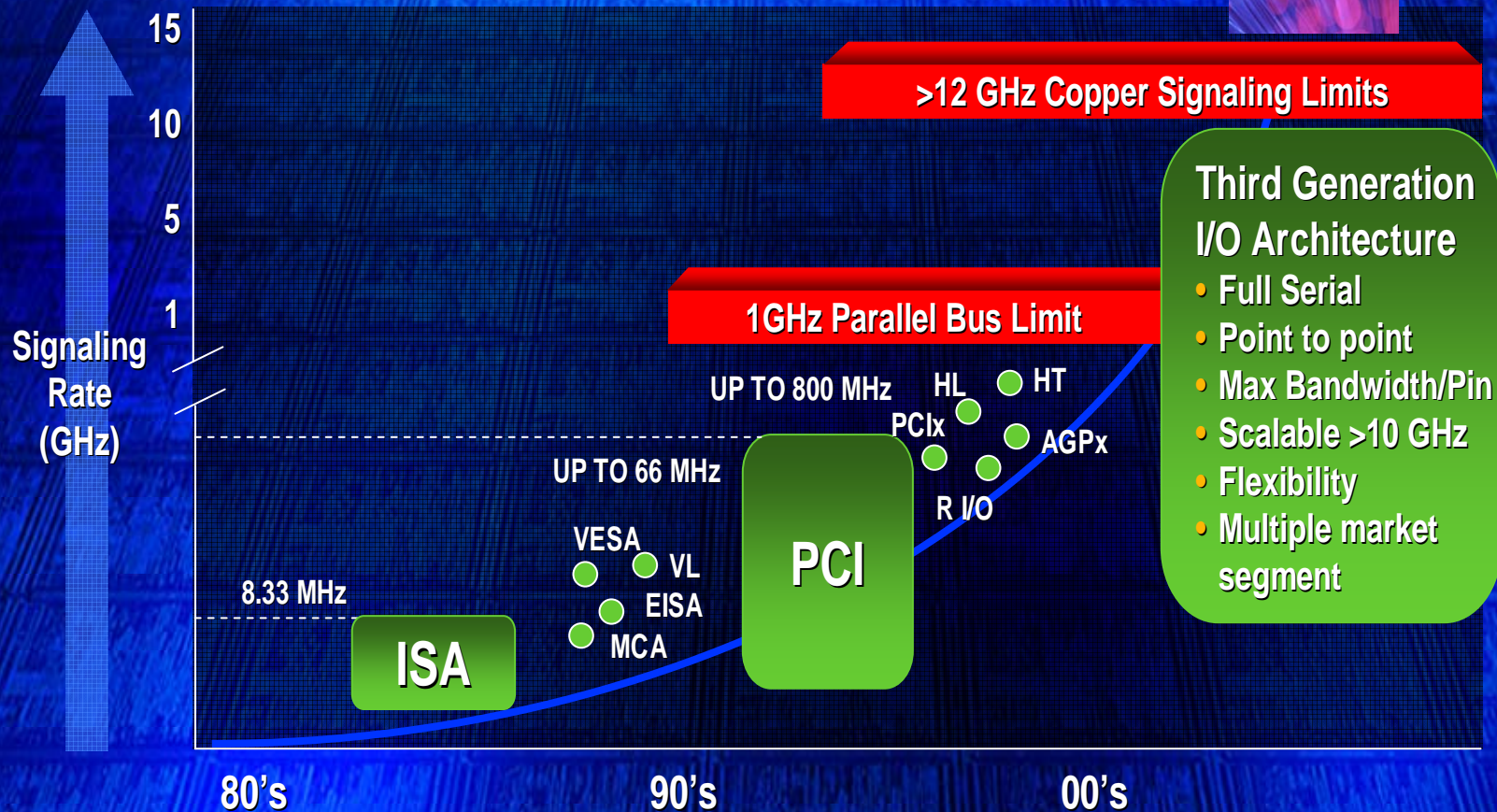


Moore's Law exponential increase in transistor densities
4 will drive equal growth in backplane data rates.



I/O Architecture Evolution

Optical Interconnects

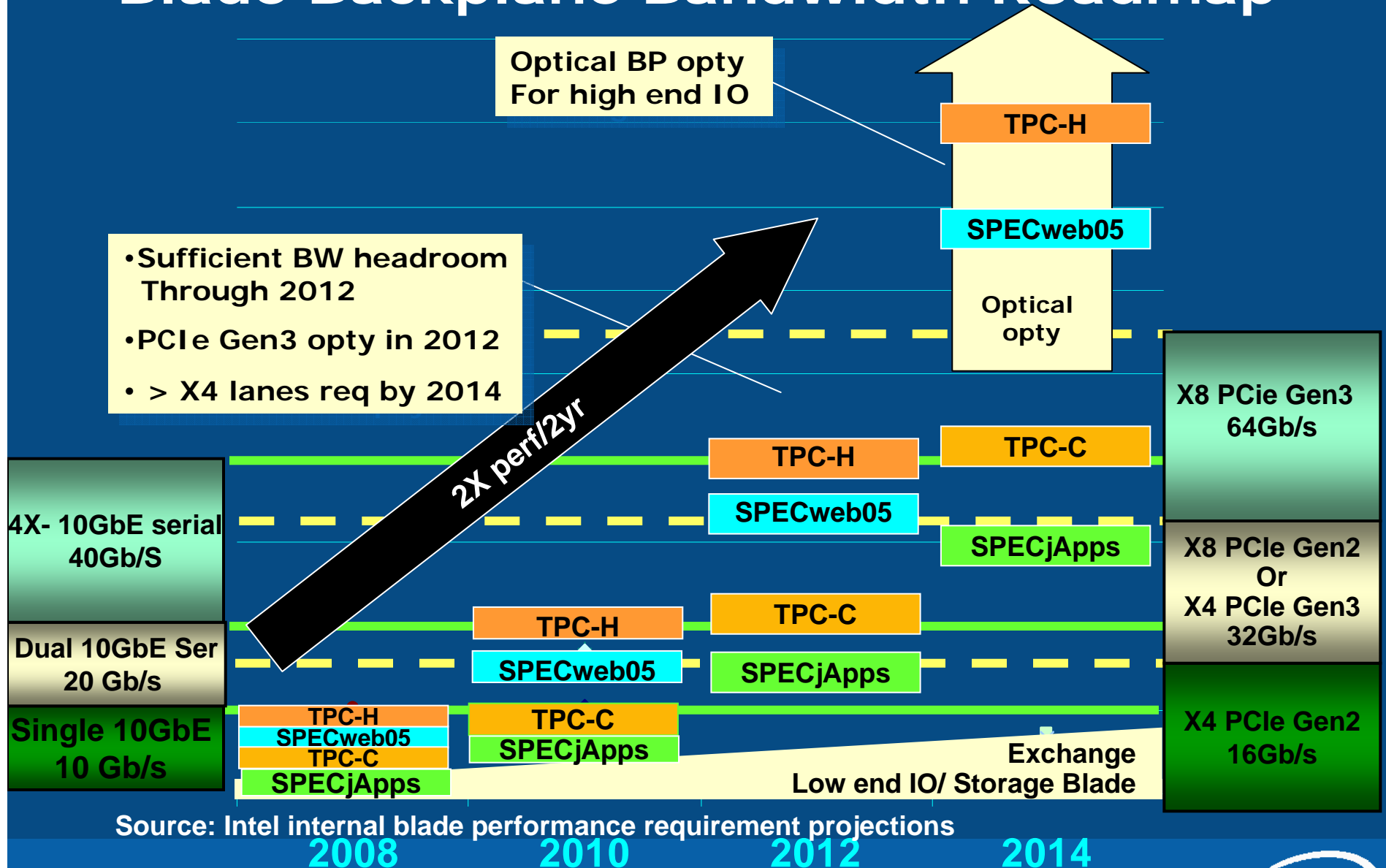


*Intel Fall IDF 2006 Presentation



Platform I/O Bandwidth capabilities increasing

Blade Backplane Bandwidth Roadmap



Blade bandwidth requirements increasing



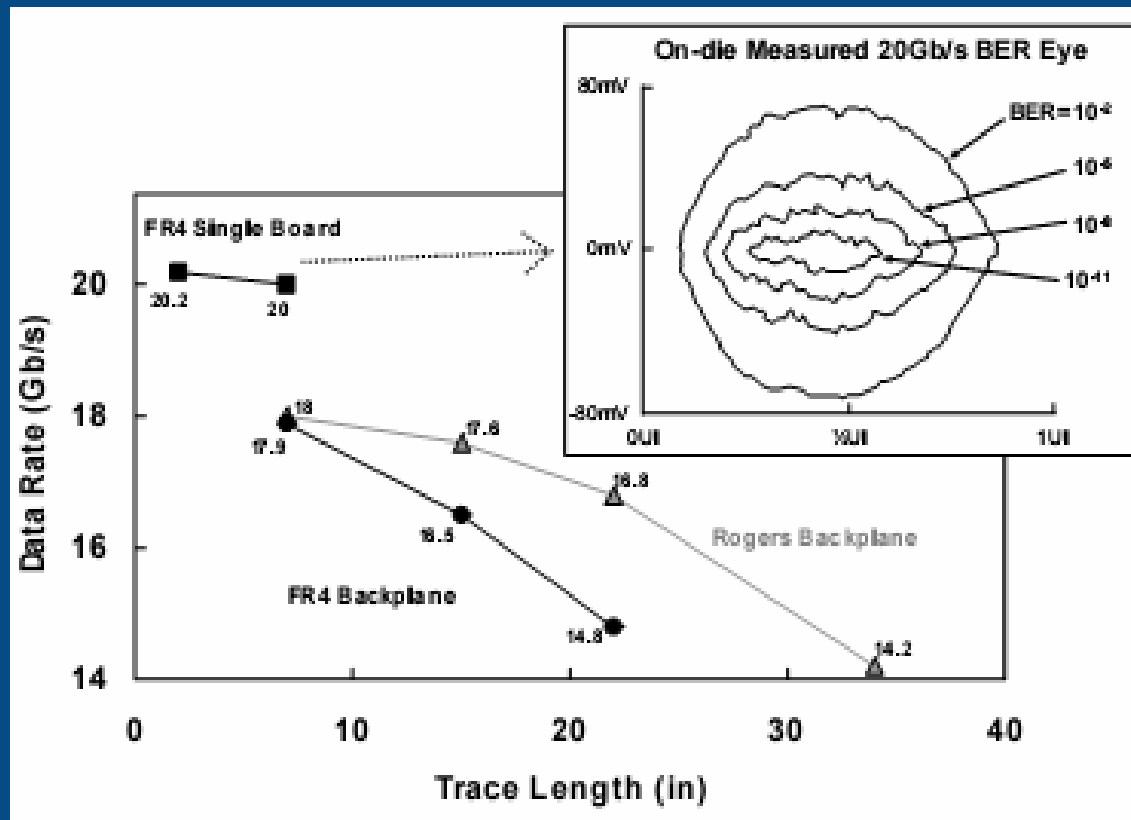
Technical Feasibility of 100GbE

- Solutions available today
 - 40G Shipping
 - Low cost DWDM (LX4) shipping
 - Future - LX5 (4x25G?)
 - VCSEL arrays (snap 12 connectors) shipping
- Integrated Silicon Photonics
 - High Data Rate - High integration a reality today.
 - 10Gb/s CMOS modulators have been shown 2005 (Intel)
 - Higher rate modulators currently being developed
- HSSG for Backplanes
 - Optical backplane on the horizon
 - 4x25 and 5x20 seem equally doable, 4x20 may be easier because of VCSEL and CMOS limitations



20Gb Electrical transmission

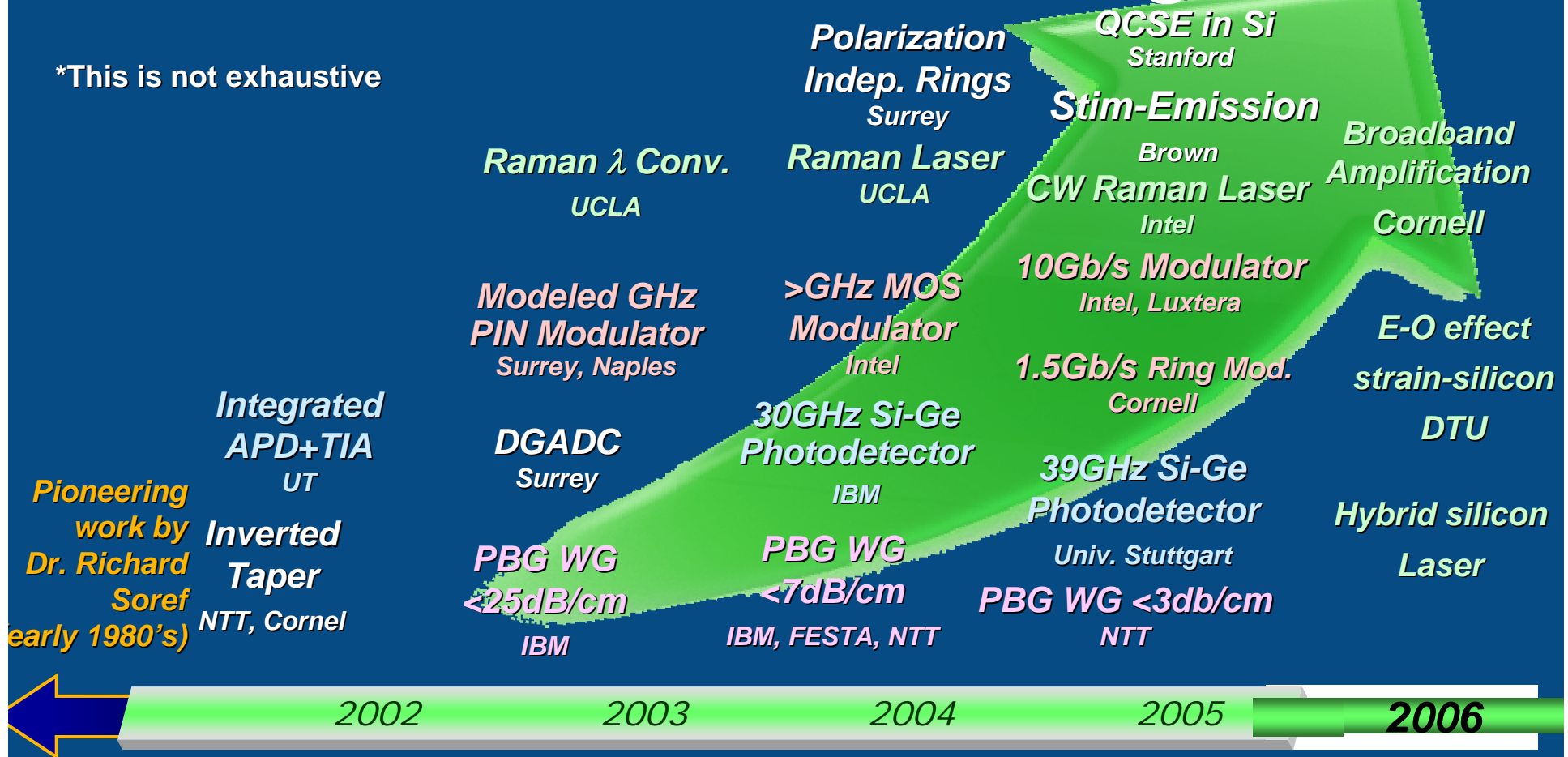
- 20 Gb transmission over FR4 using 90nm CMOS demonstrated.
- 7" FR4 with 2 sockets and packages, using Tx and Rx equalization
- Power consumption of 11.8 mW/Gb/s
- As CMOS moves to 65nm and 45nm feasible electrical rates will increase.



Technology exists today!

Technical Feasibility: Si Photonics Recent Progress

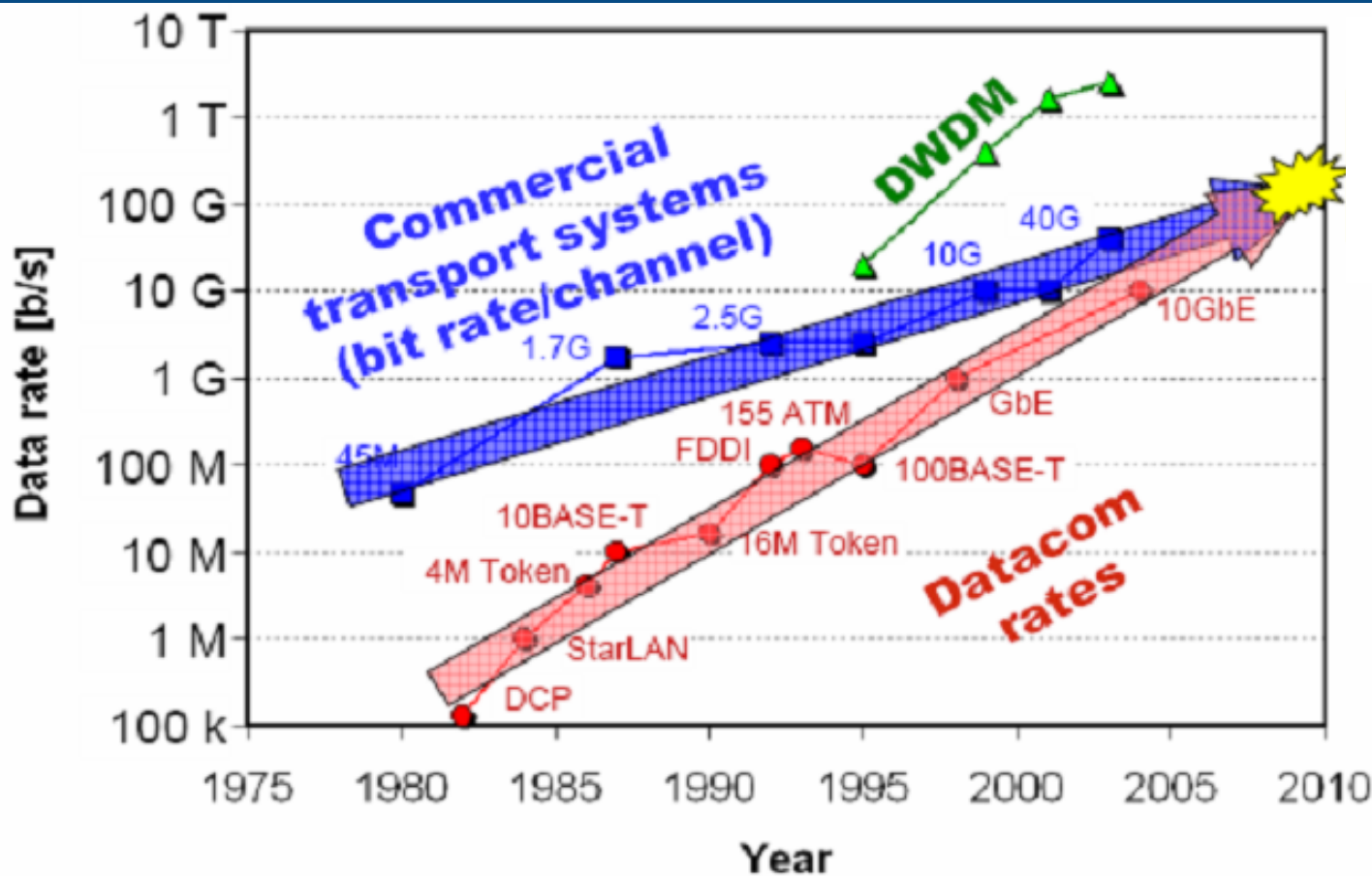
*This is not exhaustive



Device performance making
significant advances



Datacom will drive next generation technologies

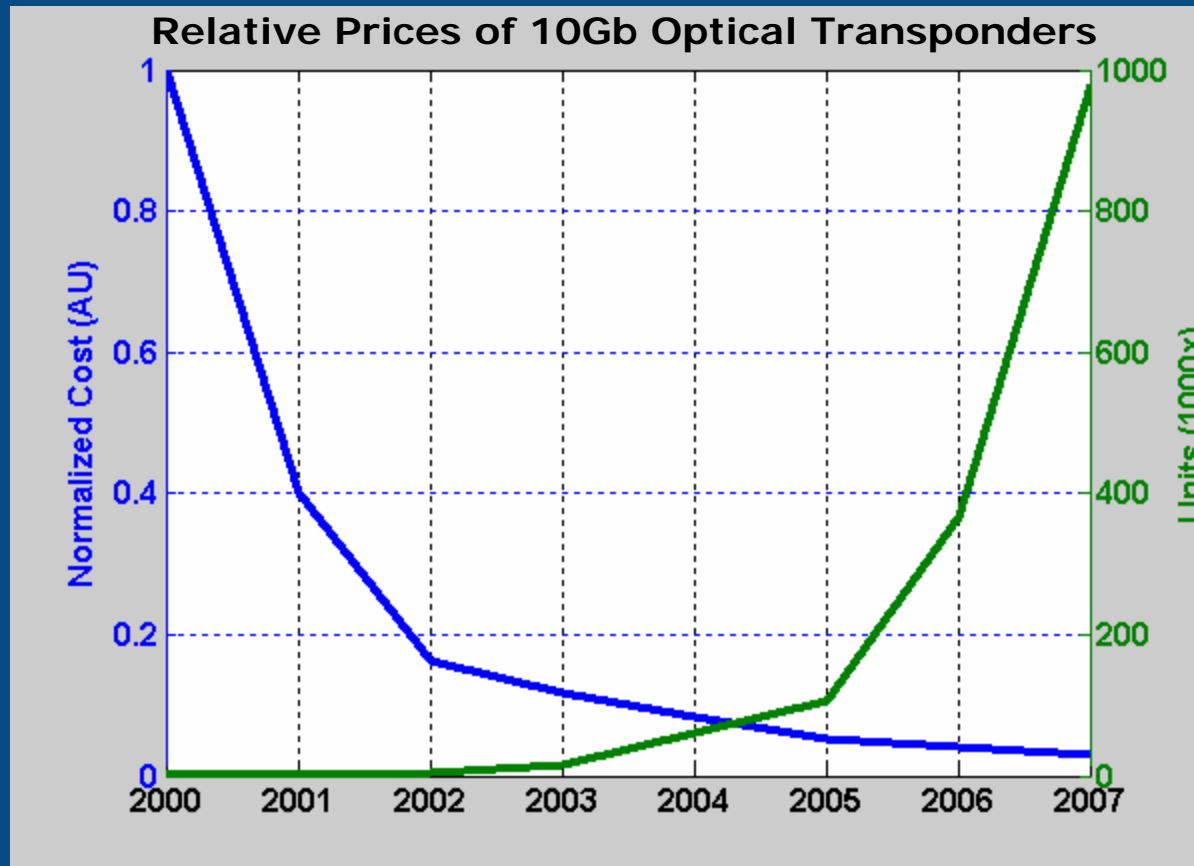


- Traditionally Datacom has trailed Telecom
- 100GE will be a disruptive technology.
- 100GE will be an inflection point, Datacom becomes the driver of technology.

Paul Toliver, OIDA 100Gb Ethernet Forum. San Jose CA, August 29 2006

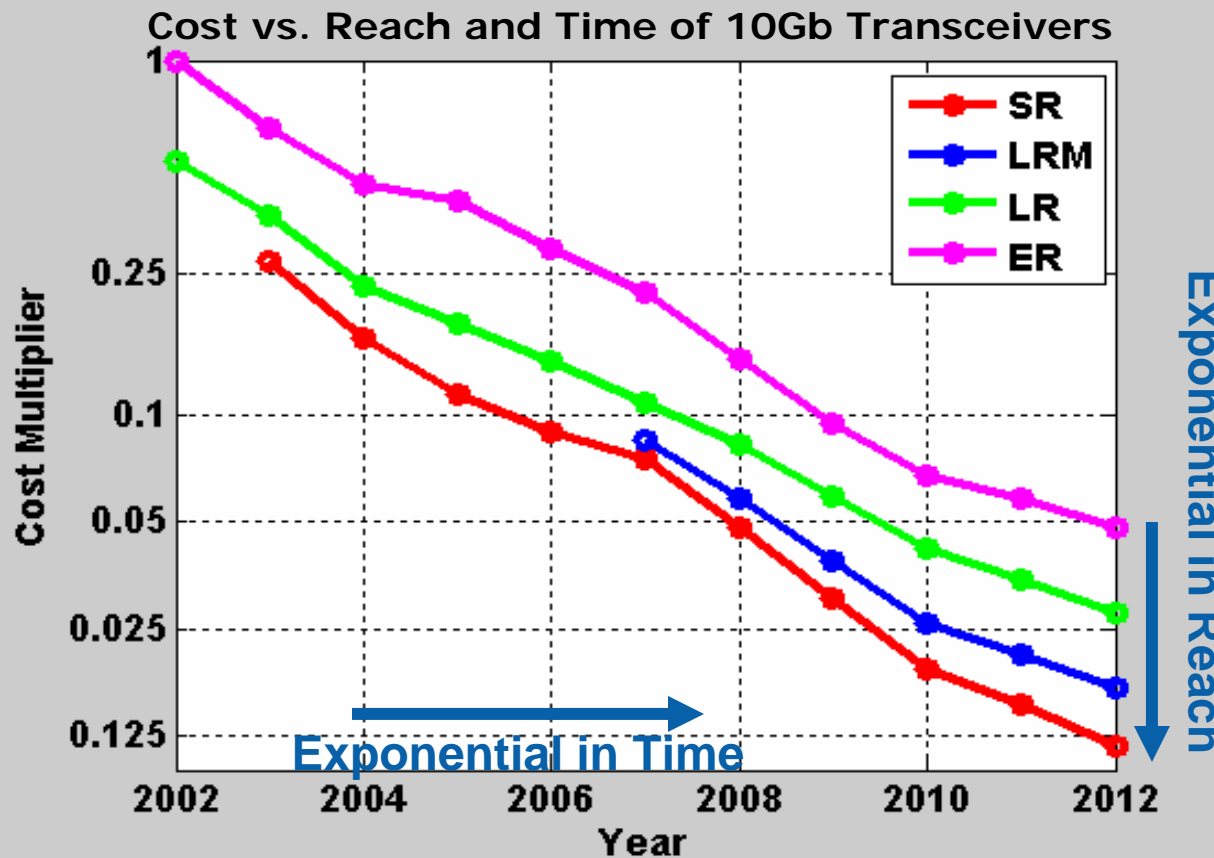
Cost vs. Units 10GE

- Volume has increased exponentially
- Cost has dropped exponentially



Increased unit volume results in lower costs

Cost vs. Reach



- Short links are cheaper.
- Cost Multiplier between long and short links has remained 'constant'
- Shorter links will drive volume and cost

Shorter reach optics (datacom) = Lower cost



100G Ethernet Considerations

- Lower Speed solutions are less interesting
 - 40GbE for backplanes is available today
 - 4 Lanes 10G-KR
 - Won't meet platform requirements by time standards are released (4+ years)
- 100GbE Solution Possibilities
 - 10 lanes of 10G BASE-KR
 - Routing problem would be quite severe
 - 4x25Gb 'KR' like link
 - CMOS implementations will be a challenge
 - Trace routing problem reasonable
 - 5x20Gb 'KR' like link
 - CMOS implementations still a challenge
 - Trace routing problem reasonable



100GE Optical Considerations

- Optical backplane on the horizon
 - time until roll out still unclear?
- Both a 4x25 and 5x20 seem equally doable.
- 5x20 may be easier because of VCSEL and CMOS limitations
 - A 5x lane split seems un-natural.
- Low number of links (4-5) links
 - high data rate CMOS and Lasers
 - large amount of equalization required for backplane
 - Relaxed routing requirements.
- High (8-10) links
 - Can leverage current KR specs.
 - Routing and connectors become an issue.
 - Number of Lasers becomes costly.



Tradeoffs for # of lanes Proposal

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Backup

Drive optics to high volume & low cost

